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INTERNATIONAL STANDARD



Metallic communication cable test methods –
Part 4-3: Electromagnetic compatibility (EMC) – Surface transfer impedance –
Triaxial method

INTERNATIONAL ELECTROTECHNICAL COMMISSION

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

METALLIC COMMUNICATION CABLE TEST METHODS –

Part 4-3: Electromagnetic compatibility (EMC) – Surface transfer impedance – Triaxial method

FOREWORD

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- Part 1-2: Metallic communication cables test methods Part 1-2: Electrical Reflection measurement correction¹
- Part 4-0: Metallic communication cable test methods Part 4-0: Electromagnetic compatibility (EMC) Relationship between surface transfer impedance and screening attenuation, recommended limits
- Part 4-1: Metallic communication cable test methods Part 4-1: Electromagnetic compatibility (EMC) Introduction to electromagnetic (EMC) screening measurements
- Part 4-2: Metallic communication cable test methods Part 4-2: Electromagnetic compatibility (EMC) Screening and coupling attenuation Injection clamp method
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- Part 4-10: Metallic communication cable test methods Part 4-10: Electromagnetic compatibility (EMC) Shielded screening attenuation test method for measuring the screening effectiveness of feed-throughs and electromagnetic gaskets double coaxial method
- Part 4-11: Metallic communication cable test methods Part 4-11: Electromagnetic compatibility (EMC) Coupling attenuation or screening attenuation of patch cords, coaxial cable assemblies, pre-connectorized cables Absorbing clamp method

¹ Under consideration.

- Part 4-12: Metallic communication cable test methods Part 4-12: Electromagnetic compatibility (EMC) Coupling attenuation or screening attenuation of connecting hardware Absorbing clamp method
- Part 4-13: Metallic communication cable test methods Part 4-13: Electromagnetic compatibility (EMC) Coupling attenuation of links and channels (laboratory conditions) Absorbing clamp method
- Part 4-14: Metallic communication cable test methods Part 4-14: Electromagnetic compatibility (EMC) Coupling attenuation of cable assemblies (Field conditions) absorbing clamp method

METALLIC COMMUNICATION CABLE TEST METHODS –

Part 4-3: Electromagnetic compatibility (EMC) – Surface transfer impedance – Triaxial method

1 Scope

This part of IEC 62153 determines the screening effectiveness of a cable shield by applying a well-defined current and voltage to the screen of the cable and measuring the induced voltage in order to determine the surface transfer impedance. This test measures only the magnetic component of the transfer impedance.

NOTE The measurement of the electrostatic component (the capacitance coupling impedance) is described in IEC 62153-4-8 [1]².

The triaxial method of measurement is in general suitable in the frequency range up to 30 MHz for a 1 m sample length and up to 100 MHz for a 0,3 m sample length, which corresponds to an electrical length less than about 1/6 of the wavelength in the sample.

2 Normative references

The following documents, in whole or in part, are normatively referenced in this document and are indispensable for its application. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC/TR 62153-4-1:2010, Metallic communication cable test methods – Part 4-1: Electromagnetic compatibility (EMC) – Introduction to electromagnetic (EMC) screening measurements

IEC 60050 (all parts), *International Electrotechnical Vocabulary (IEV)* (available at http://www.electropedia.org)

² Numbers in square brackets refer to the bibliography.

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METALLIC COMMUNICATION CABLE TEST METHODS –

Part 4-3: Electromagnetic compatibility (EMC) – Surface transfer impedance – Triaxial method

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